

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5550847

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RAJEEV KUMAR DOKANIA	05/31/2019
SASIKANTH MANIPATRUNI	05/31/2019
AMRITA MATHURIYA	05/31/2019
DEBO OLAOSEBIKAN	05/31/2019
RECEIVING PARTY DATA	
Name:	KEPLER COMPUTING INC.
Street Address:	135 DORE STREET
City:	SAN FRANCISCO
State/Country:	CALIFORNIA
Postal Code:	94103
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16428893
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	5039688233
Email:	kcampbell@ghmip.com
Correspondent Name:	KATHERINE CAMPBELL
Address Line 1:	5 CENTERPOINTE DR.
Address Line 2:	SUITE 400
Address Line 4:	LAKE OSWEGO, OREGON 97035
ATTORNEY DOCKET NUMBER:	12P006US-C1
NAME OF SUBMITTER:	KATHERINE R. CAMPBELL
SIGNATURE:	/Katherine R. Campbell/
DATE SIGNED:	05/31/2019
Total Attachments: 6	
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ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**Rajeev Kumar Dokania, Sasikanth Manipatruni
Amrita Mathuriya, Debo Olaosebikan**

hereby sell, assign, and transfer to:

Kepler Computing Inc.

a corporation of Delaware, having a principal place of business at 135 Dore Street, San Francisco, CA, 94103, USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

3D Integrated Ultra High-Bandwidth Multi-Stacked Memory

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on May 31, 20019 as

United States Application Number 16/428,893 and

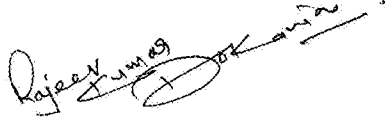
which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute

all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



Rajeev Kumar Dokania

05/31/2019

Date signed

Sasikanth Manipatruni

Date signed

Amrita Mathuriya

Date signed

Debo Olaosebikan

Date signed

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covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Rajeev Kumar Dokania

Date signed

Sasikanth M

Sasikanth Manipatruni

05/31/2019

Date signed

Amrita Mathuriya

Amrita Mathuriya

May 31st 2019

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